



Patent
Docket No.: 53092USA8A

GP 1771
#6
Green
8/10/00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Carolyn M. Ylitalo, Mario A. Perez,
Edward G. Stewart, and Patrick D. Hyde

Serial No.: 09/114,027 ✓

Filed: July 10, 1998 ✓

For: TACKIFIED THERMOPLASTIC-EPOXY
PRESSURE SENSITIVE ADHESIVES

Group Art Unit: 1771 ✓

Examiner: D. Zirker ✓

RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This Response follows the Office Action mailed May 1, 2000.

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Remarks

Claims 1-20 are pending.

Claims 1, 2 and 7-9 stand rejected under 35 U.S.C. § 102(b) as purportedly anticipated by J.P. Derwent Abst. XP002118060 ('060 reference). Applicants respectfully traverse.

The '060 reference does not purport to disclose a pressure-sensitive adhesive. Furthermore, the '060 reference does not disclose a pressure-sensitive adhesive that includes a *cured* epoxy, as described in the present claim 1. As the Examiner notes, the '060 reference suggests the addition of a curing agent. This suggestion additionally confirms that an uncured "thermosetting resin" is intended. Furthermore, this suggestion is consistent with the disclosure of a thermosetting adhesive rather than a pressure-sensitive adhesive.

Certificate of Mailing

Pursuant to 37 CFR 1.8 I certify that this correspondence is being deposited on the date indicated below with the United States Postal Service as First Class Mail addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

Date:

August 1, 2000

Signature

Harra Welle